

Silicon Carbide Power Mosfet

1. Product Information

Features

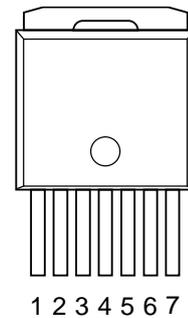
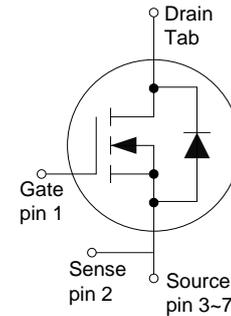
- 1700V, 570mΩ, 6A
- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low $R_{DS(on)}$
- Easy to parallel
- Simple to drive
- RoHS Compliant

Benefits

- Increased Power Density Faster Operating Frequency
- Reduction of Heat Sink Requirements
- Higher Efficiency
- Reduced EMI

Applications

- Power Factor Correction Modules
- Switch Mode Power Supplies
- DC-AC Inverters
- High Voltage DC/DC Converters



Top View
TO263-7L

Package Marking and Ordering Information

Product Name	Package	Marking	Form	Quantity (PCS)
KJSC170R570D7	TO263-7L	KJSC170R570D7	Reel & Tape	800

2. Absolute Maximum Ratings (T_J=25°C unless otherwise noted)

Symbol	Parameter	Values	Unit
V _{DS}	Drain-Source Voltage	1700	V
I _D	Continuous Drain Current, T _C =25°C	6	A
	Continuous Drain Current, T _C =100°C	4	A
I _{DM}	Peak Drain Current, Pulse width t _p limited by T _{Jmax}	12	A
V _{GSmax}	Gate-Source Voltage (Absolute maximum values)	-8/+22	V
V _{GSop}	Gate-Source Voltage (Recommended operational values)	-4/+18	V
P _D	Power Dissipation, T _C =25°C	69	W
	Power Dissipation, T _C =100°C	27	W
T _J , T _{STG}	Operating Junction and Storage Temperature	-40~150	°C
R _{θJC}	Thermal Resistance-Junction to Case	1.8	°C/W

3. Electrical Characteristics (T_C=25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Type	Max	Unit
Static Characteristics						
B _{VDS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =100μA	1700	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =1700V, V _{GS} =0V	-	1	-	μA
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =18V,	-	-	250	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =0.5mA, T _J =25°C	2.0	2.8	4.0	V
		V _{DS} =V _{GS} , I _D =0.5mA, T _J =150°C	-	1.7	-	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =18V, I _D =2A, T _J =25°C	-	570	-	mΩ
		V _{GS} =18V, I _D =2A, T _J =150°C	-	850	-	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =1000V, V _{GS} =0V, F=100kHz	-	294	-	pF
C _{oss}	Output Capacitance		-	20	-	pF
C _{rss}	Reverse Transfer Capacitance		-	3.2	-	pF
Q _g	Total Gate Charge	V _{DD} =900V, I _D =2A, V _{GS} =-4/+18V	-	27	-	nC
Q _{gs}	Gate-Source Charge		-	6	-	nC
Q _{gd}	Gate-Drain Charge		-	15	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =900V, I _D =2A, V _{GS} =-4/+18V, R _G =2.5Ω	-	6	-	ns
t _r	Turn-on Rise Time		-	21	-	ns
t _{d(off)}	Turn-off Delay Time		-	13	-	ns
t _f	Turn-off Fall Time		-	61	-	ns
E _{ON}	Turn-on Energy		-	92	-	mJ
E _{OFF}	Turn-off Fall Time Energy		-	12	-	mJ
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage	V _{GS} =-4V, I _S =2A, T _J =25°C	-	4.7	-	V
		V _{GS} =-4V, I _S =2A, T _J =150°C	-	4.2	-	V
I _S	Continuous Diode Forward Current	V _{GS} =-4V, T _J =25°C	-	8	-	A
		V _{GS} =-4V, T _J =100°C	-	4	-	A
I _{rrm}	Peak Reverse Recovery Current	V _{GS} =-4V, I _{SD} =2A, V _R =900V, di _F /dt=1100A/μs	-	35	-	A
T _{rr}	Reverse Recovery Time		-	3.3	-	ns
Q _{rr}	Reverse Recovery Charge		-	40	-	nC

4. Typical Characteristics

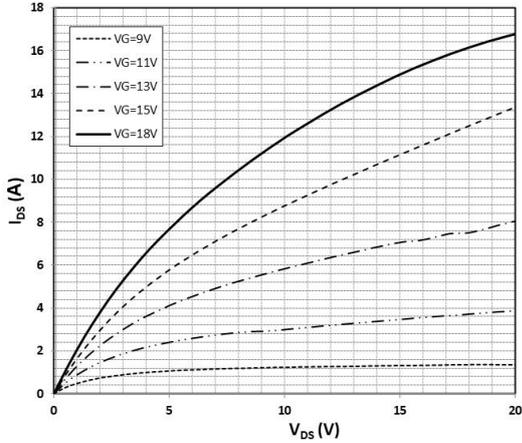


Figure 1. Output Characteristics
 $T_J=25^{\circ}\text{C}$

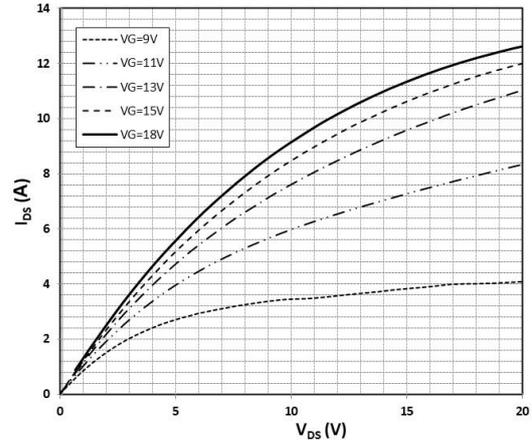


Figure 2. Output Characteristics
 $T_J=150^{\circ}\text{C}$

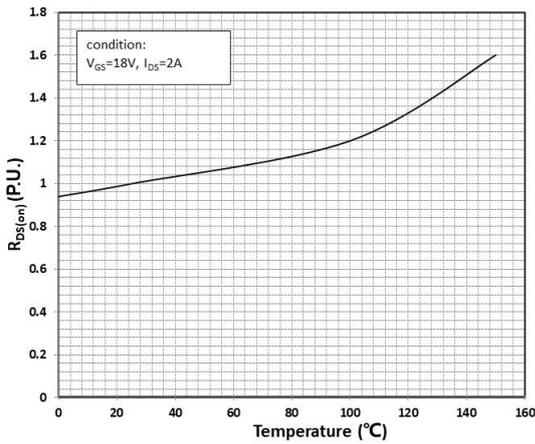


Figure 3. Normalized On-Resistance vs. Temperature

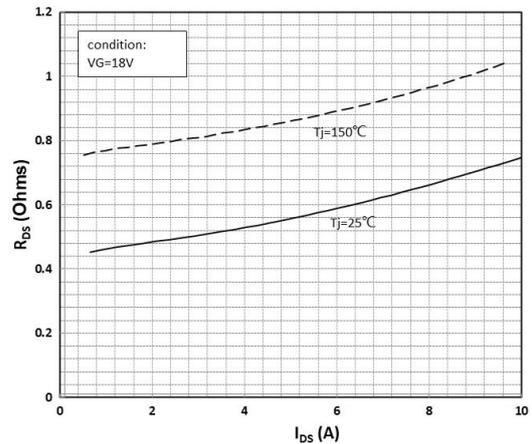


Figure 4. On-Resistance vs. Drain Current For Various Temperatures

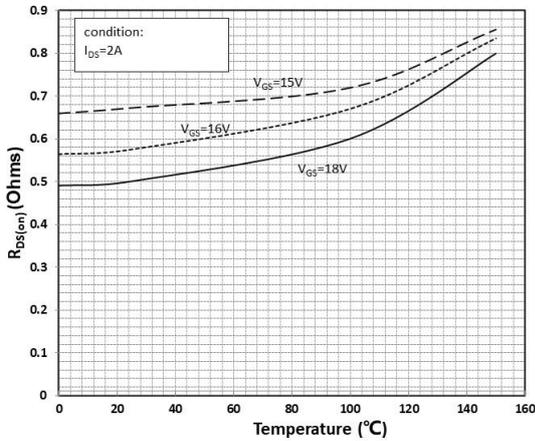


Figure 5. On-Resistance vs. Temperature For Various Gate Voltage

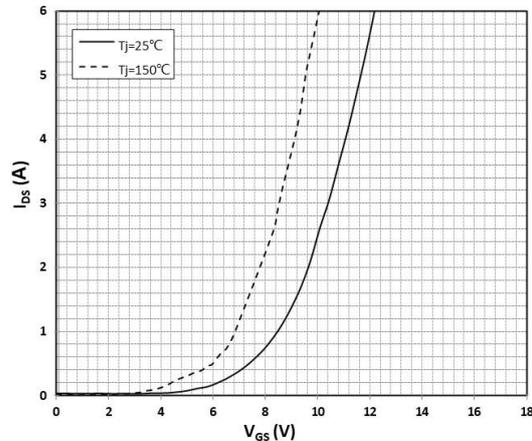


Figure 6. Transfer Characteristic for Various Junction Temperatures
 $V_{DS}=20\text{V}$

4. Typical Characteristics(cont.)

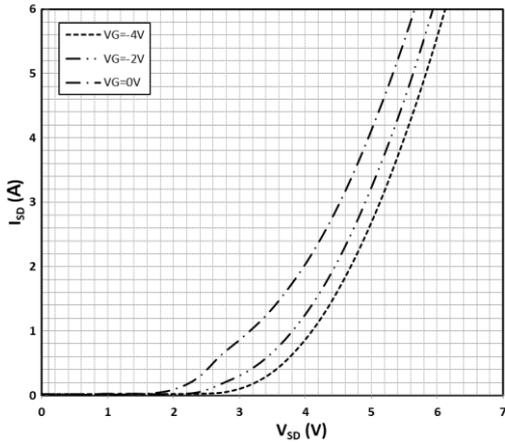


Figure 7. Body Diode Characteristics
 $T_J=25^{\circ}\text{C}$

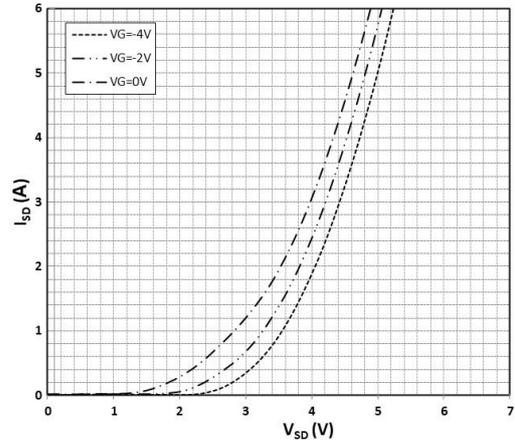


Figure 8. Body Diode Characteristics
 $T_J=25^{\circ}\text{C}$

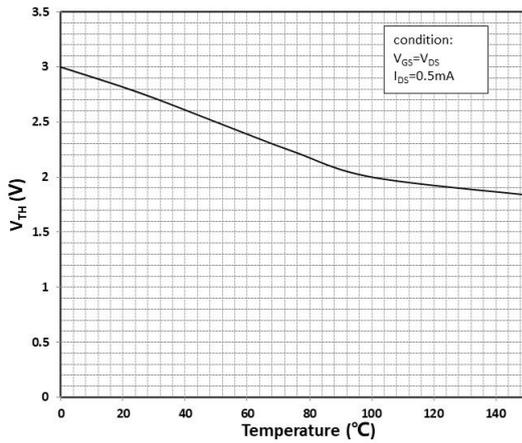


Figure 9. Threshold Voltage vs. Temperature

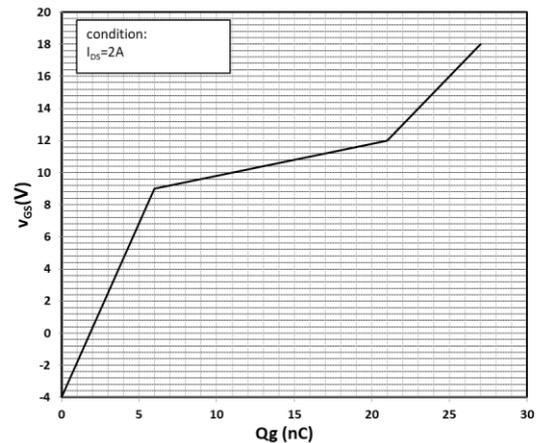


Figure 10. Gate Charge Characteristics

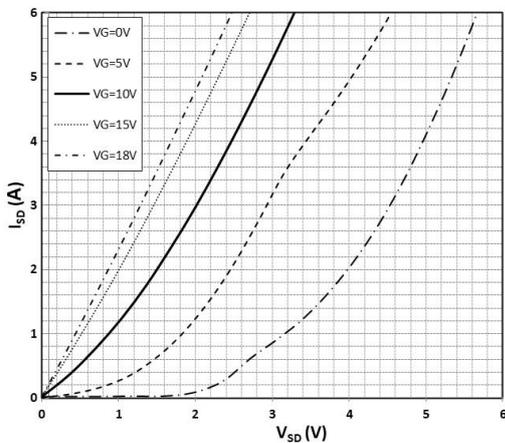


Figure 11. 3rd Quadrant Characteristics
 $T_J=25^{\circ}\text{C}$

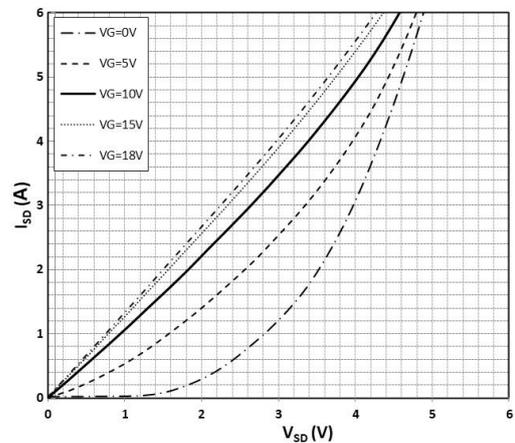


Figure 12. 3rd Quadrant Characteristics
 $T_J=150^{\circ}\text{C}$

4. Typical Characteristics(cont.)

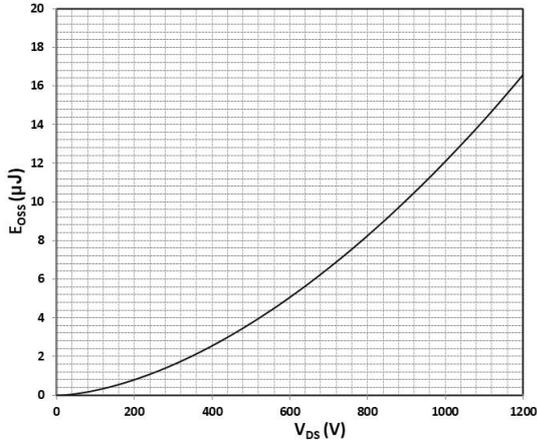


Figure 13. Output Capacitor Stored Energy

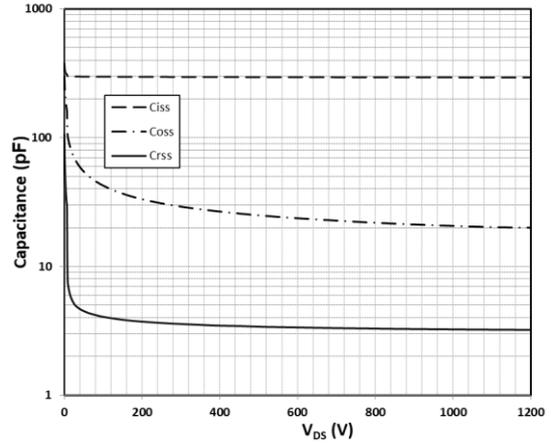


Figure 14. Capacitances vs. Drain-Source

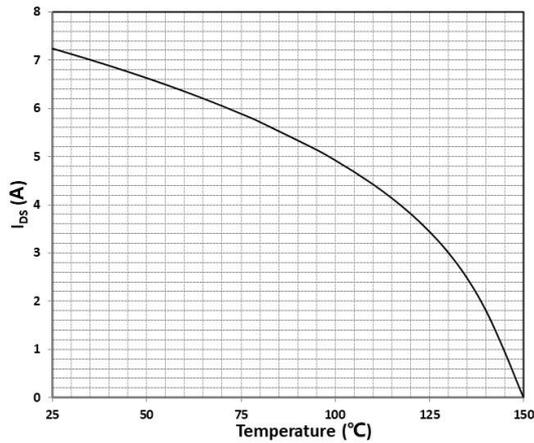


Figure 15. Continuous Drain Current Derating vs. Case Temperature

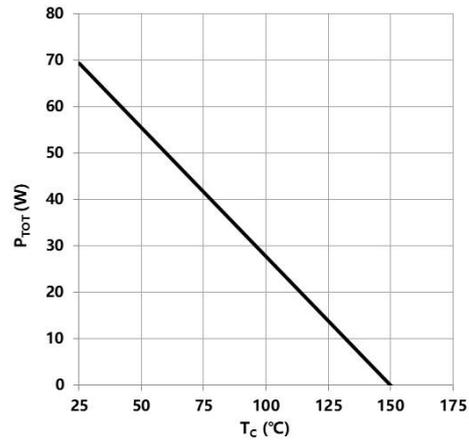


Figure 16. Maximum Power Dissipation Derating vs. Case Temperature

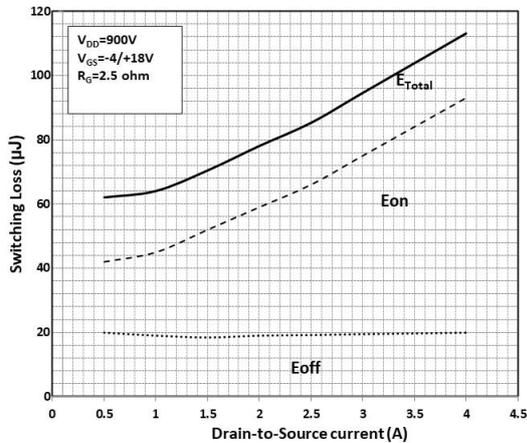


Figure 17. Clamped Inductive Switching Energy vs. Drain Current

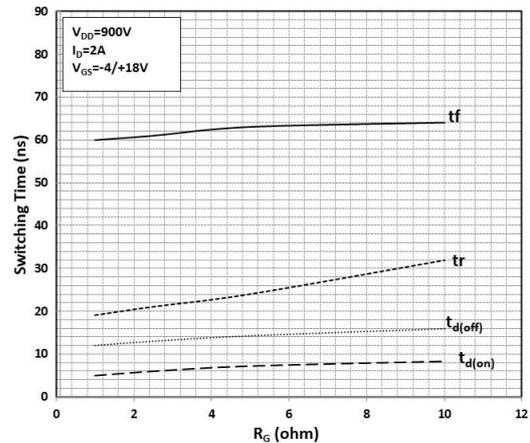


Figure 18. Switching Times vs. R_G

4. Typical Characteristics(cont.)

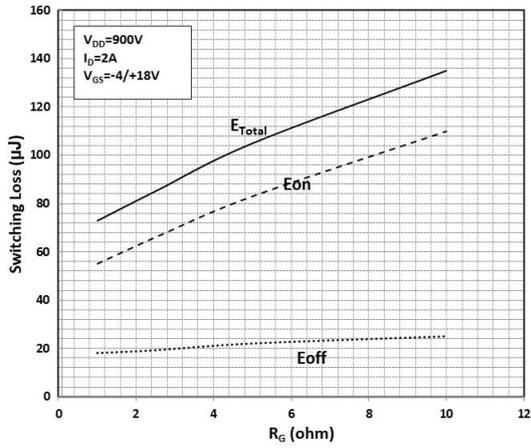


Figure 19. Clamped Inductive Switching Energy vs. R_G

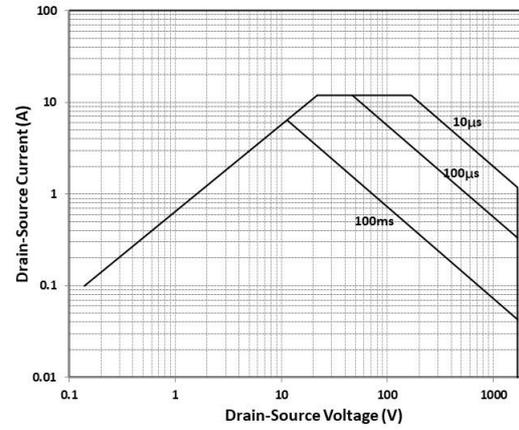
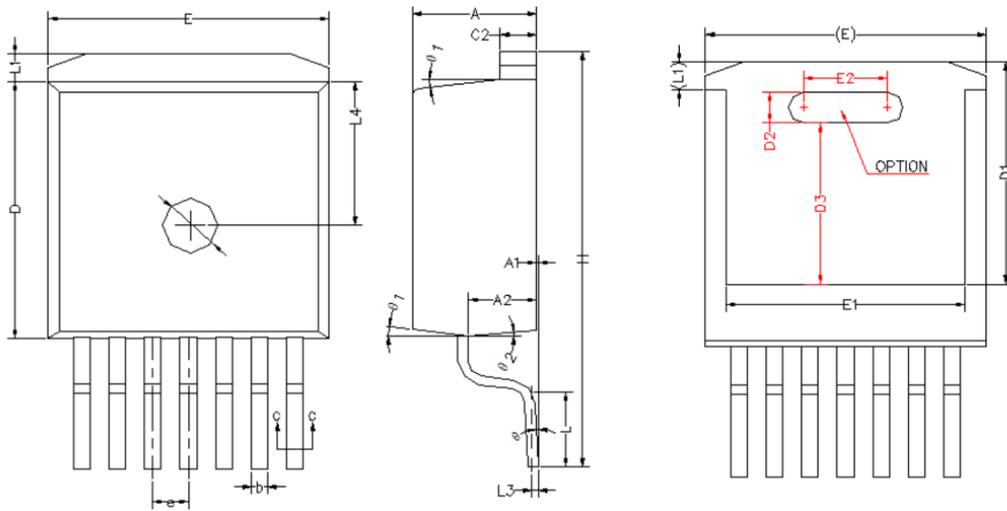


Figure 21. Safe Operating Area

5. Package Mechanical Data

TO263-7L Package



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	4.30	4.40	4.50
A1	-	0.10	0.25
A2	2.30	2.40	2.50
b	0.56	-	0.69
b1	0.55	0.60	0.65
c	0.37	-	0.44
c1	0.36	0.38	0.40
c2	1.22	1.27	1.32
D	9.15	9.25	9.35
D1	7.90	8.00	8.10
D2	1.00	1.11	1.20
D3	5.70	5.80	5.90
E	9.90	10.00	10.10
E1	8.40	8.50	8.60
E2	2.90	3.00	3.10
e	1.17	1.27	1.37
H	14.60	14.95	15.35
L	2.40	2.70	2.90
L1	0.90	1.00	1.10
L3		0.25 BSC	
L4		2.50 REF	
θ	0°	-	8°
θ1	5°	7°	9°
θ2	3°	5°	7°